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4354728	4895521	6214180
4509087	4906198	6220870
5848912	4932876	6224392
4586772	4998892	6227876
4804339	5009606	6231353
5208580	5017159	6247938
5282756	5055055	6252175
6075290	5035659	6267606
6128197	5190486	6336269
4469389	5195350	6452406
6215670	5215471	6538214
6215670	5252916	6773272
4799589	5447442	6802720
6049976	5486657	6818840
4538675	5496183	4803600
4542784	5559675	4994710
5476211	5589669	4249709
5635775	5647765	4264840
5828226	5655930	4274532
4538878	5664968	4339942
4795602	5683256	4460914
4820207	5697322	4498725
4929193	5735712	4510558
4954104	5752839	4524253
4969259	5795191	4530711
5002507	5811982	4532841
5575666	5818248	4534022
5581122	5838160	4536948
5852871	5876215	4597480
5908333	5885091	4625576
5928000	5893765	4854755
6155887	5893779	4860539
4381134	5913687	4861177
4415220	5914614	4904608
4446505	5938451	4997788
4475781	5990696	4999538
4596437	6000975	4999696
4606589	6039580	5188545
4769907	6052895	5197371
4784620	6072324	5265334
4821411	6135783	5293809
4824380	6178629	5308267
4831728	6181149	5351865
4836806	6190214	5374267
4846705	6191600	5414930
4857018	6197171	5422535
4857019	6208155	5468683
4878861	6214180	5471929
4878863	6220870	5487259
4885126	6224392	5524511

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Set Items Description

S1 8107222 S SEMICONDUCTOR? OR SEMI()CONDUCTOR? OR SUBSTRATE? OR WAFER? OR IC? ? OR
INTEGRATED()CIRCUIT? OR CHIP? OR ASIC? OR PACKAGE? ?
S2 14111 S PIN(2N)CONTACT? ?
S3 34948 S CONTACT? ?(2N)END?
S4 415237 S FIRST(2N)(SIDE OR PORTION OR SEGMENT? OR PART? OR SECTION?)
S5 23314 S FORM?(3N)PLACE
S6 3273087 S COUPL??????
S7 165 S S1 AND S2 AND S3
S8 5 S S4 AND S7
S9 5 RD (unique items)
S10 0 S S5 AND S7
S11 18 S S2 AND S3 AND S4
S12 2 S S11 AND S6
S13 2 S S12 NOT S9
S14 2 RD (unique items)
S15 11 S (BUILT()IN? OR BUILD()IN? OR BUILTIN? OR BUILDIN?)(3N)(S2 OR S3)
S16 11 RD (unique items)
S17 11 S16 NOT (S14 OR S9) FROM 2, 6, 8, 25, 34, 36, 65, 92, 94, 95, 99, 103, 104, 144, 239, 241, 434, 647, 315,
347, 350, 31, 248, 23, 46, 68, 60, 33, 335, 294
S18 1 S S16 AND S1
S19 3 S (BUILT()IN)(3N)(S2 OR S3)
S20 3 RD (unique items)

? show files

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[File 36] **MetalBase** 1965-20050926

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[File 65] **Inside Conferences** 1993-2005/Sep W4

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[File 315] **ChemEng & Biotec Abs** 1970-2005/Aug

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[File 347] **JAPIO** Nov 1976-2005/Apr(Updated 050801)

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[File 350] **Derwent WPIX** 1963-2005/UD,UM &UP=200561

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9/3,K/2 (Item 1 from file: 350) Links
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011768349 **Image available**
WPI Acc No: 1998-185259/199817
XRPX Acc No: N98-147103

**IC socket used during testing of electrical
property of IC - has link member which slidably connects
cover and operation pin and is supported by main body**

Patent Assignee: ENPLAS KK (ENPL-N)
Number of Countries: 001 Number of Patents: 001
Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 10041037	A	19980213	JP 96198016	A	19960726	199817 B

Priority Applications (No Type Date): JP 96198016 A 19960726

Patent Details:

Patent No	Kind	Lan Pg	Main IPC	Filing Notes
JP 10041037	A	9	H01R-033/76	

**IC socket used during testing of electrical
property of IC -**

...Abstract (Basic): The **IC** socket has a socket main body in
which a rectangular **IC** mount stand is formed. A cover (11)
is attached with the main body. A set...

...provided, which are attached at opposing side edges of main body with
constant space. An **IC chip** (24) is placed on
the stand, whose terminal lead contacts the upper surface of
contact pin. A link member (22) connects the
cover and the operation pin (21) slidably...

...A **first** projection **part** (19a) of a press
member (19) is projected upwards and whose **end**
contacts operation part of the cover. The second
projection part (19b) of the press member prolongs to inner horizontal
direction and presses the edge of the **IC**. An arm is
provided, which suppresses the second projection part. The pressing of
the second...

...ADVANTAGE - Simplifies structure. Ejects **IC**
chip simply...

Title Terms: **IC**;

9/3,K/3 (Item 2 from file: 350) Links

Derwent WPIX

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010933380 **Image available**

WPI Acc No: 1996-430330/199643

XRFX Acc No: N96-362695

**Top open type IC socket for accommodation of J
vento lead type IC package - uses
contact pin which comprises pair of contact and
connection parts, for providing vertical support to inserted
IC package at both ends**

Patent Assignee: ENPLAS CORP (ENPL-N)

Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 8213130	A	19960820	JP 95315150	A	19911218	199643 B

Priority Applications (No Type Date): JP 91U104429 U 19911218

Patent Details:

Patent No	Kind	Lan Pg	Main IPC	Filing Notes
JP 8213130	A	6	H01R-033/76	

**Top open type IC socket for accommodation of J
vento lead type IC package - ...**

**...uses contact pin which comprises pair of
contact and connection parts, for providing vertical support to inserted
IC package at both ends**

**...Abstract (Basic): The IC socket consists of a square shaped
main body (1) and a guide member (2) which...**

**...which is perpendicularly slidable, is attached to the upper part of the
main body. An IC position board (4) is provided at the
central part of the main body. A contact pin
(5) which comprises a press part (5a), a
first contact part (5b), a second contact
part (5c), a spring part (5d) and a connection part (5e) and a base
(5f) is positioned outside the IC position card, at a
fixed space. The press part forms the upper end of the
contact pin and the branched
first contact part forms the inner side of
the press part bottom. The spring part is formed in the turning point,
at the bottom side of the first contact
part and the branched second contact part is formed in the
spring part bottom side, in the same direction as that of the
first contact part.**

...

...from the base. A slope part (7) which presses the press part and evacuates the **first contact part** is provided at the cover. An **IC package** (8) is supported vertically by contact pins, at both sides. The press contact is released, by releasing the press action at the lead or main body side of the **IC package** which is held by the **first contact part** of the **contact pin**.

...

...ADVANTAGE - Prevents deformation of leads of **IC package**. Prevents **IC package** from being separated from socket due to vibration or impact. Enables easy insertion of **IC package** from both front and back directions

...Title Terms: **IC**;

9/3,K/4 (Item 3 from file: 350) Links

Derwent WPIX

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009729794 **Image available**

WPI Acc No: 1994-009644/199402

Related WPI Acc No: 1994-076342; 1994-083756; 1998-035135

XRPX Acc No: N94-007761

**Image bearing member e.g. photosensitive drum for
electrophotographic copier - has weight arranged within photosensitive
drum asymmetrically w.r.t. centre of substrate supporting
image bearing layer**

Patent Assignee: CANON KK (CANO)

Inventor: IKEMOTO I; KOBAYASHI K; MIZUTANI M; NISHIBATA A; NODA S; SASAGO Y
; SEKINE K; SHIMIZU Y; TSUDA T; WATANABE K

Number of Countries: 010 Number of Patents: 010

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week	
EP 577404	A1	19940105	EP 93305106	A	19930629	199402	B
CN 1083228	A	19940302	CN 93102537	A	19930129	199524	
US 5488459	A	19960130	US 9384489	A	19930628	199611	
US 5602623	A	19970211	US 9310071	A	19930126	199712	
			US 95455725	A	19950531		
EP 577404	B1	19970827	EP 93305106	A	19930629	199739	
DE 69313374	E	19971002	DE 93613374	A	19930629	199745	
			EP 93305106	A	19930629		
MX 187259	B	19971203	MX 93509	A	19930129	199936	
KR 132555	B1	19981116	KR 931166	A	19930129	200029	
CA 2088237	C	20010605	CA 2088237	A	19930127	200136	
CN 1058794	C	20001122	CN 93102537	A	19930129	200472	

Priority Applications (No Type Date): JP 92194661 A 19920630; JP 92217421 A
19920724; JP 9317851 A 19930111

Patent Details:

Patent No	Kind	Lan	Pg	Main IPC	Filing Notes
EP 577404	A1	E	76	G03G-015/00	
Designated States (Regional): DE ES FR GB IT					
CN 1083228	A			G03G-015/00	
US 5488459	A		70	G03G-005/00	
US 5602623	A		67	G03G-015/00	Div ex application US 9310071
EP 577404	B1	E	15	G03G-015/00	
Designated States (Regional): DE ES FR GB IT					
DE 69313374	E			G03G-015/00	Based on patent EP 577404
MX 187259	B			G03G-017/000	
KR 132555	B1			G03G-015/04	
CA 2088237	C	E		G03G-015/10	
CN 1058794	C			G03G-021/18	

... has weight arranged within photosensitive drum
asymmetrically w.r.t. centre of substrate supporting image

bearing layer

- ...Abstract (Basic): bearing member (9) includes an image bearing layer (9b) for bearing an image and a **substrate** (9a) for supporting the image bearing layer. A weight portion (9d) is arranged with the **substrate** asymmetrically with respect to the centre of the **substrate** in a generatrix direction, and offset from the central position (C) toward the flange gear...
- ...An earthing contact (18a) contacts the inner surface of the **substrate** of the photosensitive drum (9) and the other **end** of the **contact** abuts against a drum earth **contact pin**, for electrically earthing the drum. The earthing contact is arranged at the end of the...
- ...Abstract (Equivalent): integrally formed as a gear portion, said integrally-formed gear portion comprising a through-bore **portion** having a **first portion**, and a second **portion**, said **first portion** being disposed outside of said second portion in the axial direction of said cylindrical member and having an inner diameter that is smaller than an inner diameter of said second **portion**, said **first portion** being fitted on a drum shaft when said photosensitive drum is mounted in the image...
- ...Title Terms: **SUBSTRATE**;

9/3,K/5 (Item 4 from file: 350) Links

Derwent WPIX

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004267686

WPI Acc No: 1985-094564/198516

XRPX Acc No: N85-070856

Releasable connection device for package on PCB

- provides socket with contacts for engaging integrated circuit packages with various different lead spacings

Patent Assignee: THOMAS & BETTS CORP (THOB)

Inventor: SADIGH B A A

Number of Countries: 012 Number of Patents: 006

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week	
EP 137656	A	19850417	EP 84305566	A	19840816	198516	B
JP 60091579	A	19850522	JP 84170104	A	19840816	198527	
CA 1216644	A	19870113				198707	
US 4702706	A	19871027	US 86840279	A	19860317	198745	
EP 137656	B	19890329				198913	
DE 3477537	G	19890503				198919	

Priority Applications (No Type Date): US 83523802 A 19830816

Patent Details:

Patent No	Kind	Lan	Pg	Main IPC	Filing Notes
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EP 137656	A	E	14		
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Designated States (Regional): BE CH DE FR GB IT LI NL SE

EP 137656	B	E			
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Designated States (Regional): BE CH DE FR GB IT LI NL SE

Releasable connection device for package on PCB

...

...provides socket with contacts for engaging integrated circuit packages with various different lead spacings

...Abstract (Basic): The socket (22) receives a dual-in-line **package** (26) such as an EPROM. The housing (28) of the socket is generally T-shaped...

...34) extending through the centre of the housing, and each is able to receive a **contact pin**. Second **end** parts (30b) project laterally from the central housing and are supported in a respective recess...

...Contact members (30c,30d) for leads of the **integrated circuit package** are provided in each second part (30b). A space (53) between contact members (30c) is equal to the

spacing between leads (24a) of a **package** (24) and a space (54) between the contact members (30d) equals the spacing between leads (26a) of a further **package** (26...

- ...ADVANTAGE - Soldering of **IC package** leads to socket contacts gives permanent connection which is gas-tight and resistant to severe...
- ...Abstract (Equivalent): of an electric component (12) comprising: an elongate insulative housing (28) for receiving an electric **package** (24,26) having a plurality of conductive leads (24a,26a) extending therefrom, said housing including...
- ...a plurality of conductive electrical contacts (30) supported on said housing, each contact including a **first end portion** (30a) disposed in a respective one of said apertures for disengageable electrical engagement with a...
- ...lateral portions, said contact members adapted for selective engagement with said leads of said electric **package**. (11pp)
- ...Abstract (Equivalent): The electrical connector comprises an **integrated circuit (IC) package** having several leads in dual-in-line configuration. A socket in the device comprises an...
- ...and two groups of contacts, arranged in laterally spaced, longitudinally corresp. positions. Each of the **contacts** has an **end** portion selectively plated, with gold for example, for detachable connection to a conductor of the...
- ...A second **end** of the **contacts** is selectively tin-plated and soldered to the leads of the **IC package**. The second end portion of each of the contacts is formed to have at least two laterally spaced contact members, providing selective securement of **IC packages** having different laterally spaced leads. (7pp)a
- ...Title Terms: **PACKAGE**;